L Number	Hits	Search Text	DB	Time stamp
-	3	pellet and (GaAsP or Gallium adj arsenic	USPAT;	2003/07/25
	_	adj phosphorus) adj mixed adj crystal	EPO; JPO; DERWENT	10:51
-	7	(light adj emitting adj diode or LED) and (GaAsP or Gallium adj arsenic adj	USPAT; EPO; JPO;	2003/07/25 10:57
-		phosphorus) adj mixed adj crystal	DERWENT) , _ ,
-	0	((light adj emitting adj diode or LED) and (GaAsP or Gallium adj arsenide adj	USPAT;	2003/07/25
		phosphide)adj3 mixed adj crystal) and raugh\$3 adj surface	EPO; JPO; DERWENT	10.58
_	1	((light adj emitting adj diode or LED)	USPAT;	2003/07/25
	_	and (GaAsP or Gallium adj arsenide adj	EPO; JPO;	10:58
		phosphide)adj3 mixed adj crystal) and rough\$3 adj surface	DERWENT	
_	1	(light adj emitting adj diode or LED) and	USPAT;	2003/07/25
		(GaAsP or Gallium adj arsenide adj	EPO; JPO;	10:59
		phosphide) adj3 mixed adj crystal and	DERWENT	
_	2	rough\$3 adj3 surface (light adj emitting adj diode or LED) and	USPAT;	2003/07/25
1		(GaAsP or Gallium adj arsenide adj	EPO; JPO;	10:59
		phosphide)adj3 mixed adj crystal and	DERWENT	
	^-	rough\$3 with surface	, uana m	2002/02/05
-	26	(light adj emitting adj diode or LED) and (GaAsP or Gallium adj arsenide adj	USPAT; EPO; JPO;	2003/07/25
{		phosphide)adj3 mixed adj crystal	DERWENT	10.55
-	0	solder adj20 bump adj20 reliability and	USPAT;	2003/09/01
		((under adj ball adj metal) or UBM) and	EPO; JPO;	17:18
]		passivation adj20 layer and reflow\$3 and	DERWENT	
		((T adj shape\$d) or "T-shaped") and contact adj20 pad		
_	О	solder adj20 bump and ((under adj ball	USPAT;	2003/09/01
		adj metal) or UBM) and passivation adj20	EPO; JPO;	17:19
		layer and reflow\$3 and ((T adj shape\$d)	DERWENT	
_	0	or "T-shaped") and contact adj20 pad solder adj20 bump and ((under adj ball	USPAT;	2003/09/01
})	adj metal) or UBM) and passivation adj20	EPO; JPO;	17:19
		layer and reflow\$3 and ((T adj shape\$1)	DERWENT	
	_	or "T-shaped") and contact adj20 pad		
-	0	solder adj20 bump and (under adj ball adj metal or UBM) and passivation adj20 layer	USPAT;	2003/09/01
		metal or UBM) and passivation adj2U layer and reflow\$3 and (T adj shape\$1 or	EPO; JPO; DERWENT	17:19
		"T-shaped") and contact adj20 pad		
-	0	solder adj20 bump and (under adj ball adj	USPAT;	2003/09/01
		metal or UBM) and passivation adj20 layer	EPO; JPO;	17:20
		and reflow\$3 and (T adj shape\$1 or T-shaped) and contact adj20 pad	DERWENT	
-	0	solder adj20 bump and under adj ball adj	USPAT;	2003/09/01
		metal and passivation adj20 layer and	EPO; JPO;	17:20
}		reflow\$3 and (T adj shape\$1 or T-shaped)	DERWENT	
_	0	and contact adj20 pad solder adj20 bump and under adj ball adj	USPAT;	2003/09/01
		metal and passivation adj20 layer and	EPO; JPO;	17:21
		reflow\$3 and contact adj20 pad	DERWENT	
-	0	solder adj20 bump and under adj ball adj	USPAT;	2003/09/01
		metal and passivation and reflow\$3 and contact adj20 pad	EPO; JPO; DERWENT	17:21
_	0	solder adj20 bump and under adj ball adj	USPAT;	2003/09/01
		metal and passivation and contact adj20	EPO; JPO;	17:21
ļ	_	pad	DERWENT	
_	0	solder and under adj ball adj metal and	USPAT;	2003/09/01
		passivation and contact adj20 pad	EPO; JPO; DERWENT	17:22
_	0	solder and under adj ball adj metal and	USPAT;	2003/09/01
		passivation and contact adj pad	EPO; JPO;	17:22
_		colden and Upper and management	DERWENT	2002/20/22
-	23	solder and UBM and passivation and contact adj pad	USPAT; EPO; JPO;	2003/09/01 17:22
		contact adj pad	DERWENT	11.22
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